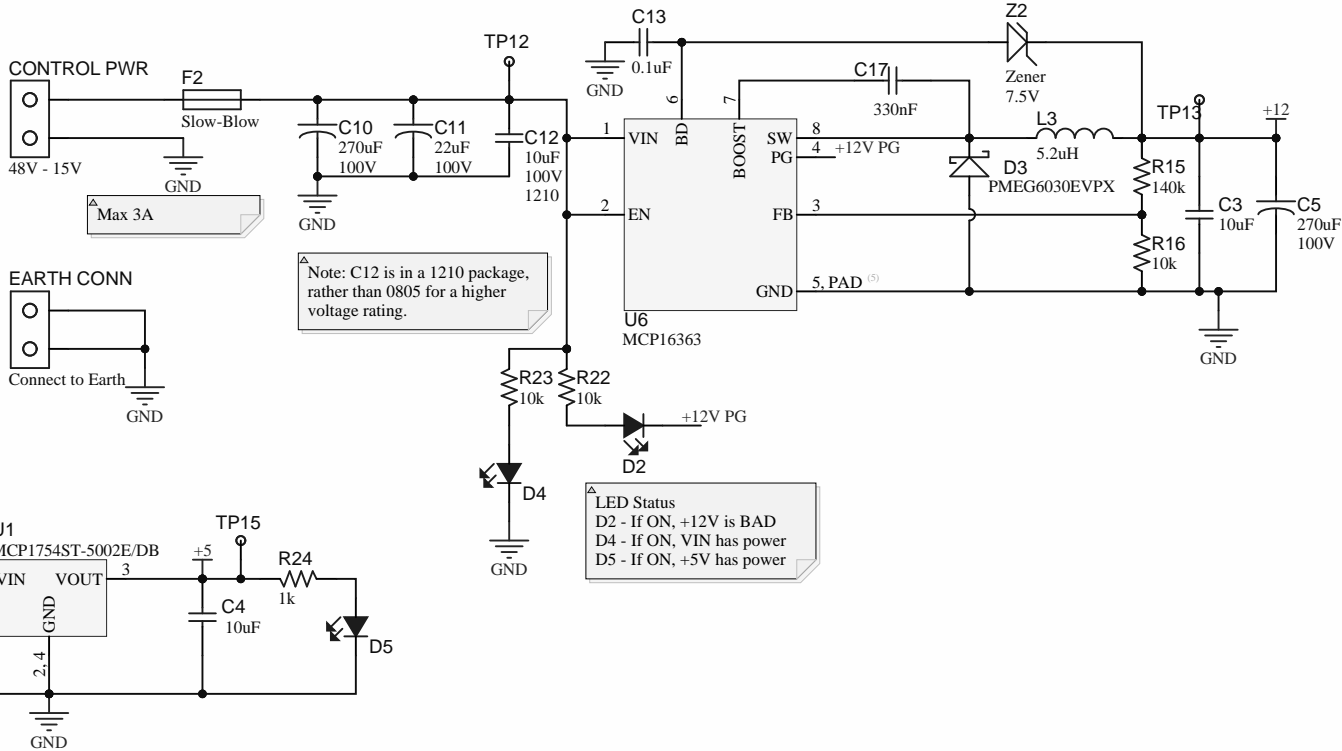
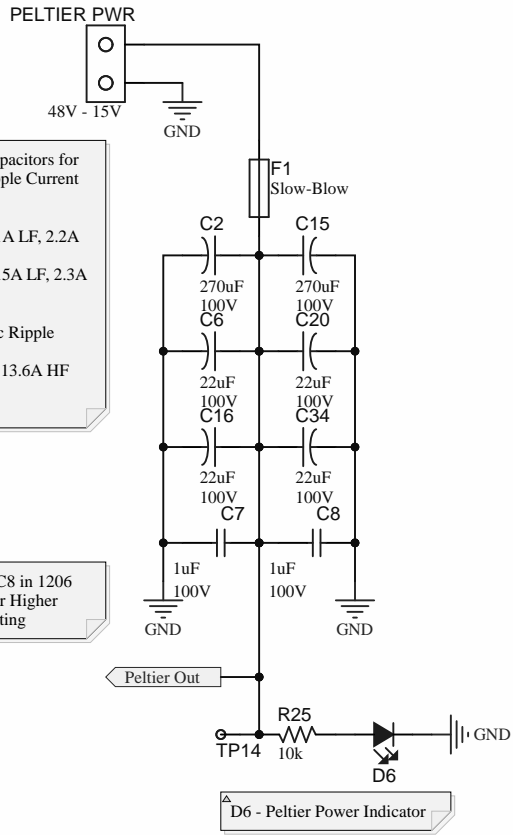




Parallel Capacitors for Higher Ripple Current Capacity.

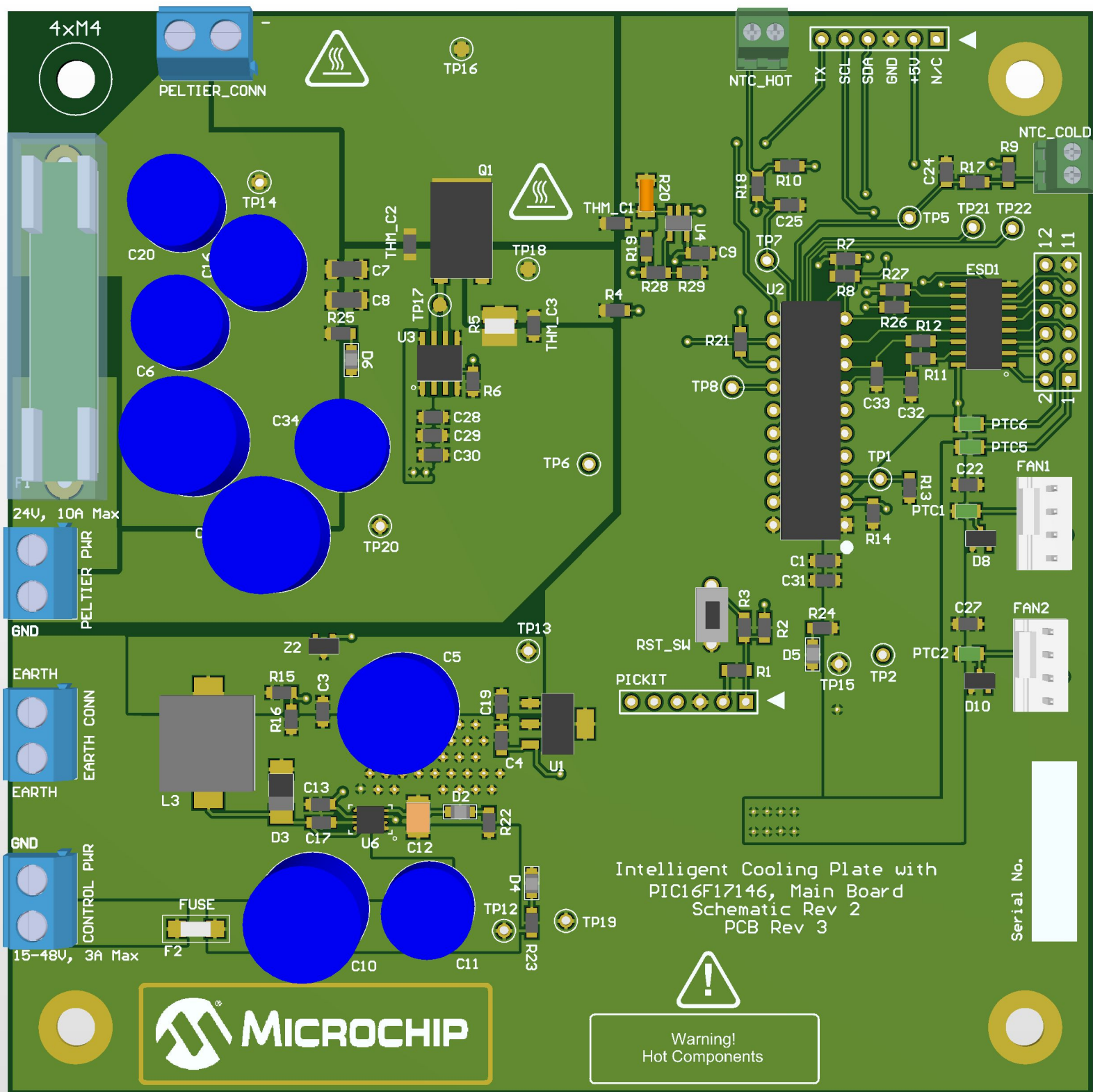
270uF - 1.1A LF, 2.2A HF
22uF - 0.115A LF, 2.3A HF

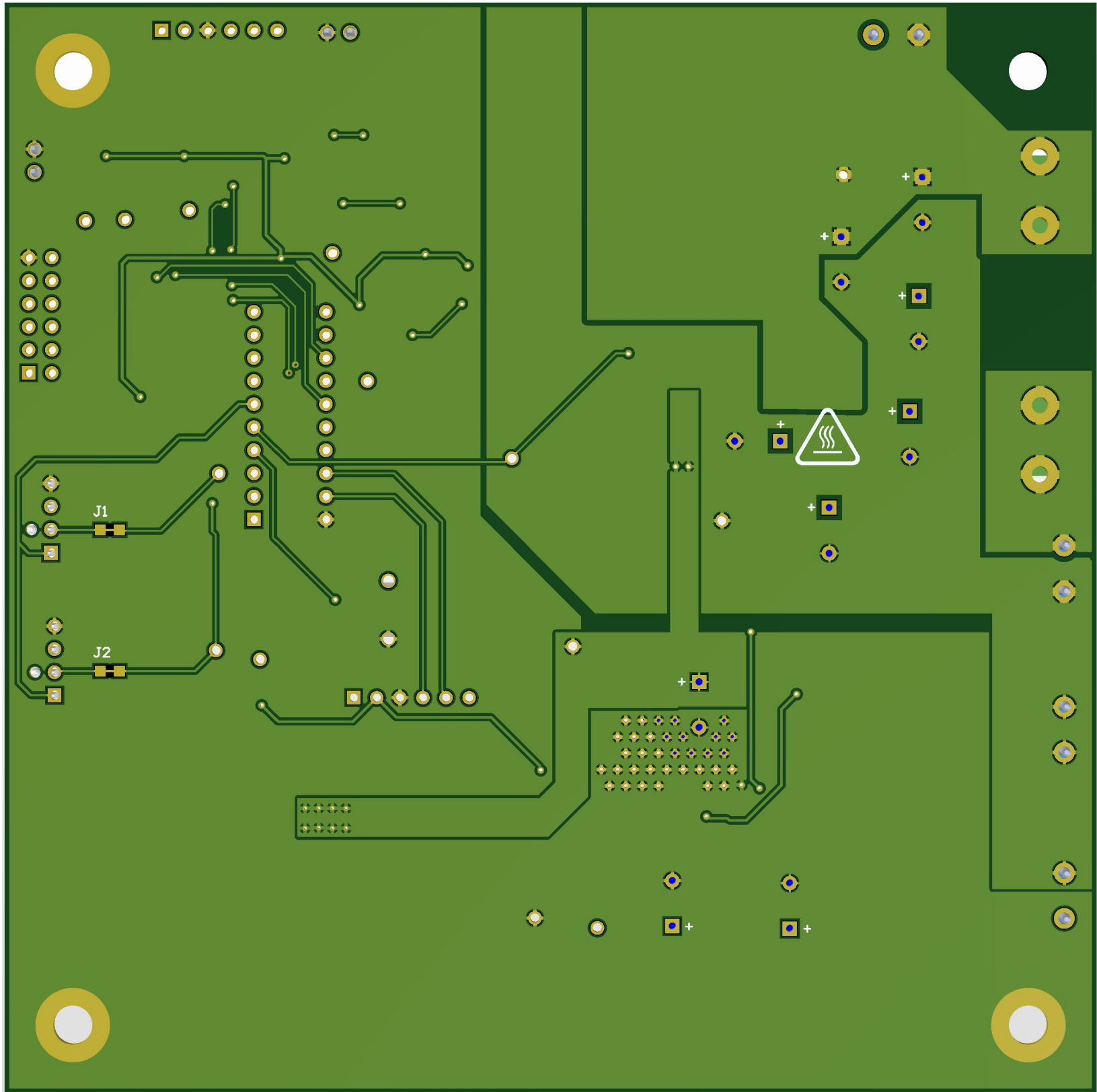
Electrolytic Ripple Capacity
2.43 A LF, 13.6A HF

Note: C7, C8 in 1206 Package for Higher Voltage Rating

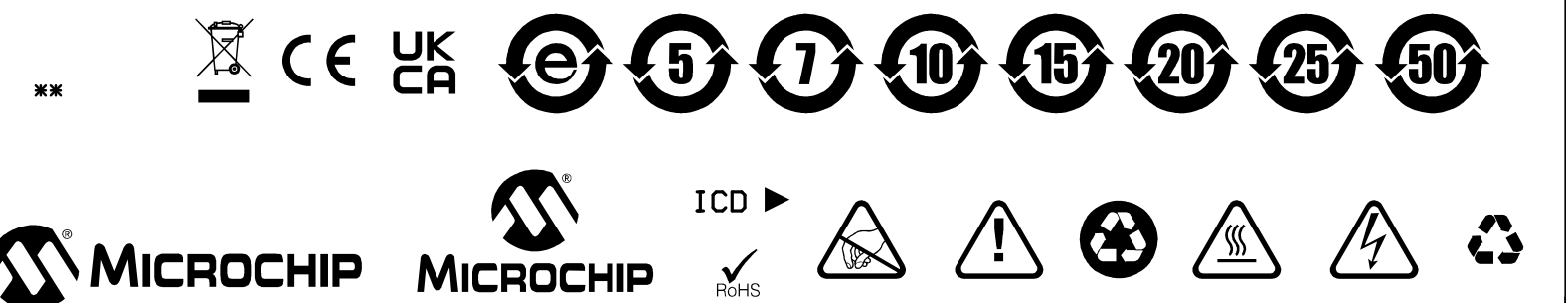
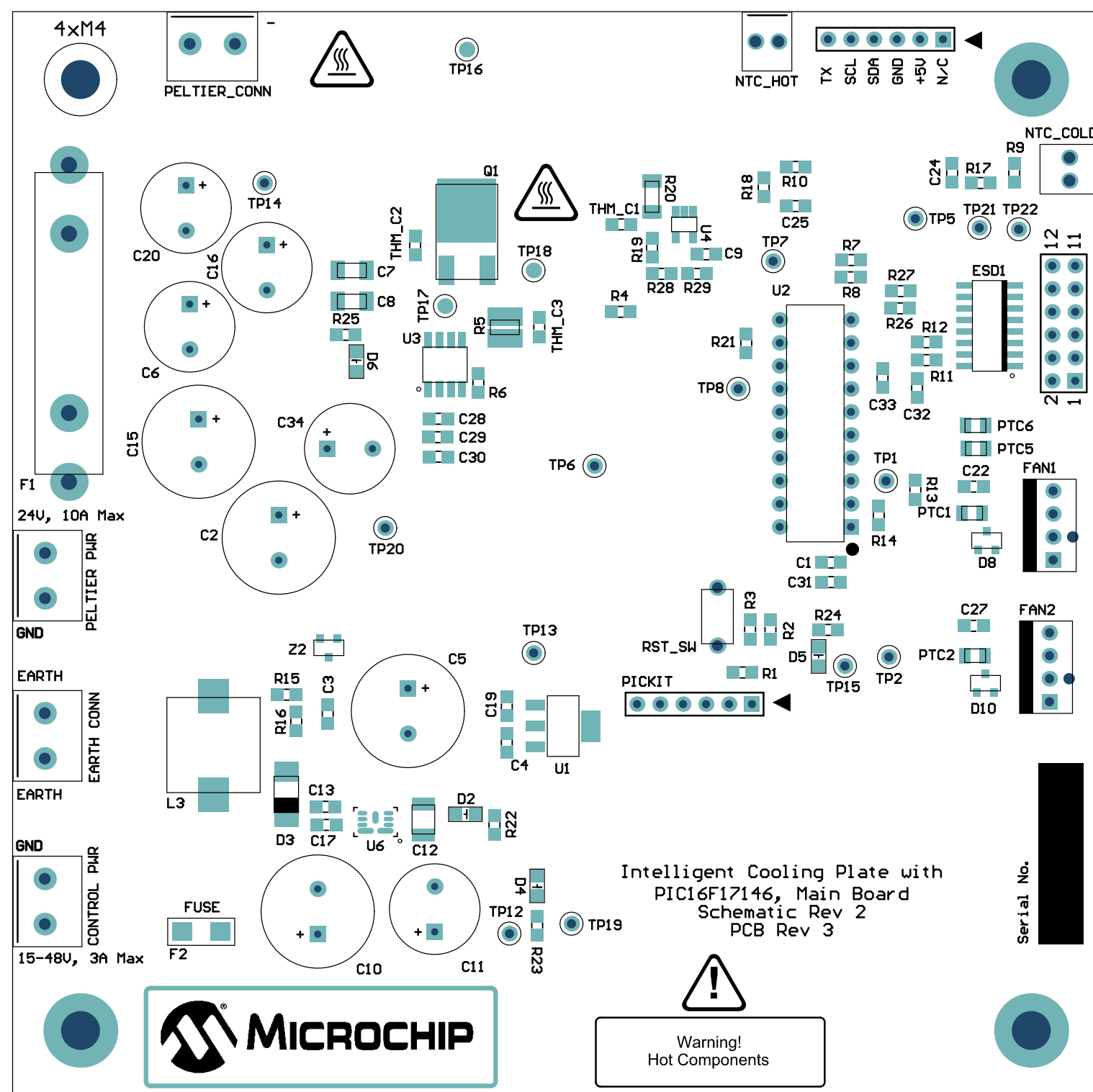


Project Owner: Robert Perkel		 MICROCHIP			
PCB Layout Contact: Robert Perkel					
PartNumber: **	Project Title Intelligent Cooling Plate with PIC16F17146, Main	Variant: [No Variations]			
Sheet Title Cold Plate Demo - Power Supply		<div>Designed with</div>  <div>Altium.com</div>			
Size B	SCH #: 03-**			Rev: 2	Date: 12/8/2022
	PCB #: 04-**			Rev: 3	Sheet 2 of 2
File: powerSupply.SchDoc					






5		6	
REV	ECO	Comments	Date

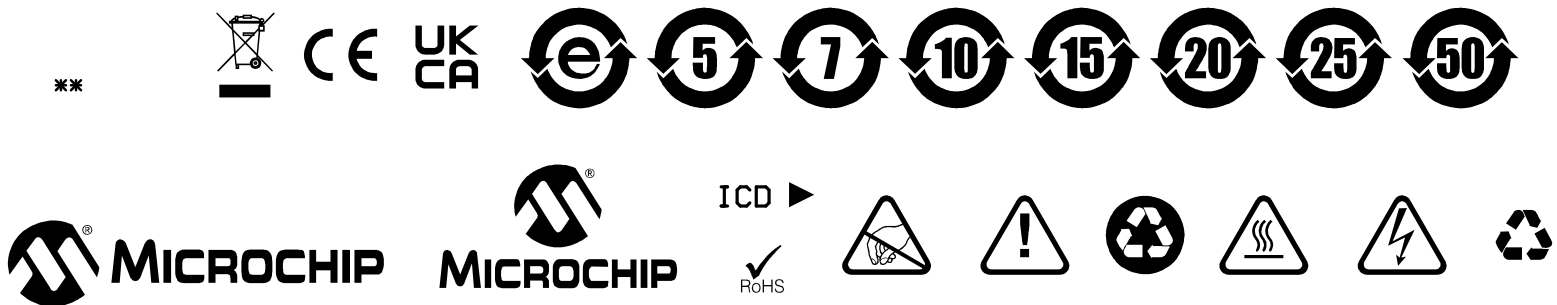
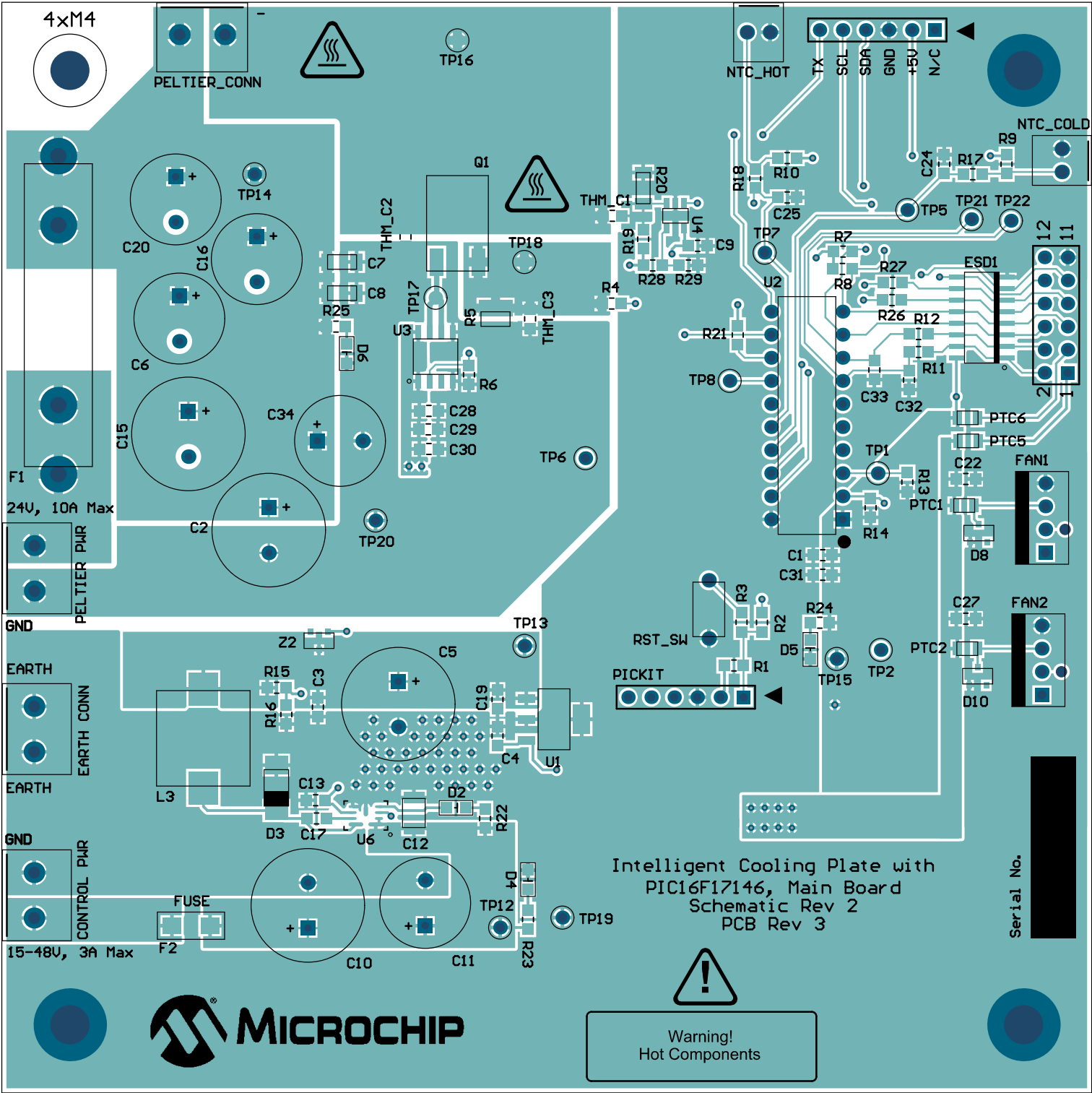


dsPICDEM.net™	mTouch®	chipKIT™
dsPICDEM™	MPLAB®	dsPIC®
PICDEM.net™	PICkit™	PIC®
PICDEM™	PICtail™	

 MICROCHIP Microchip Technology Inc. 2355 W. Chandler Blvd. Chandler, AZ 85224	TITLE:		PART NUMBER: **	
	Intelligent Cooling Plate with PIC16F17146, Main			
	PCB Layout Contact:	GERBER FILE:		
	Robert Perkel	'TOP Silk'		
Project Owner:	BOARD NUMBER:		DATE:	
Robert Perkel	04-**		12/8/2022	
PCB FILE NAME:	LAYER NAME:	REV:	10mm	
171xx Cold Plate.PcbDoc	BOARD (Rev 1.2)	3	400mil	

D
Board

5	6
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dsPICDEM.net™ mTouch® chipKIT™
dsPICDEM™ MPLAB® dsPIC®
PICDEM.net™ PICkit™ PIC®
PICDEM™ PICtail™



TITLE: Intelligent Cooling Plate with PIC16F17146, Main Board		PART NUMBER: **	
PCB Layout Contact: Robert Perkel		GERBER FILE: 'TOP Copper & Silk'	
Project Owner: Robert Perkel		BOARD NUMBER: 04-**	DATE: 12/8/2022
PCB FILE NAME: 171xx Cold Plate.PcbDoc		LAYER NAME: Board (142)	REV: 3

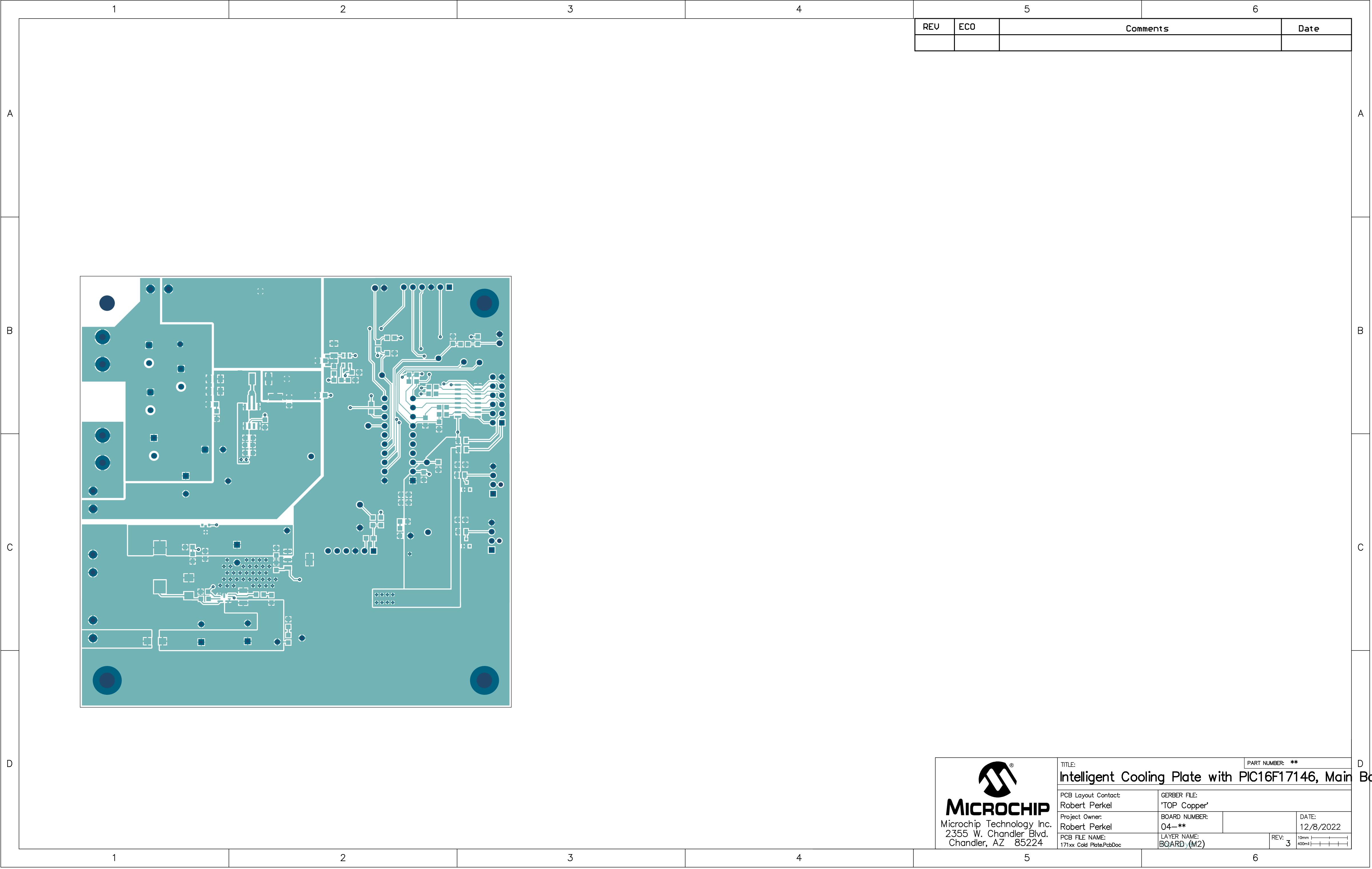
A

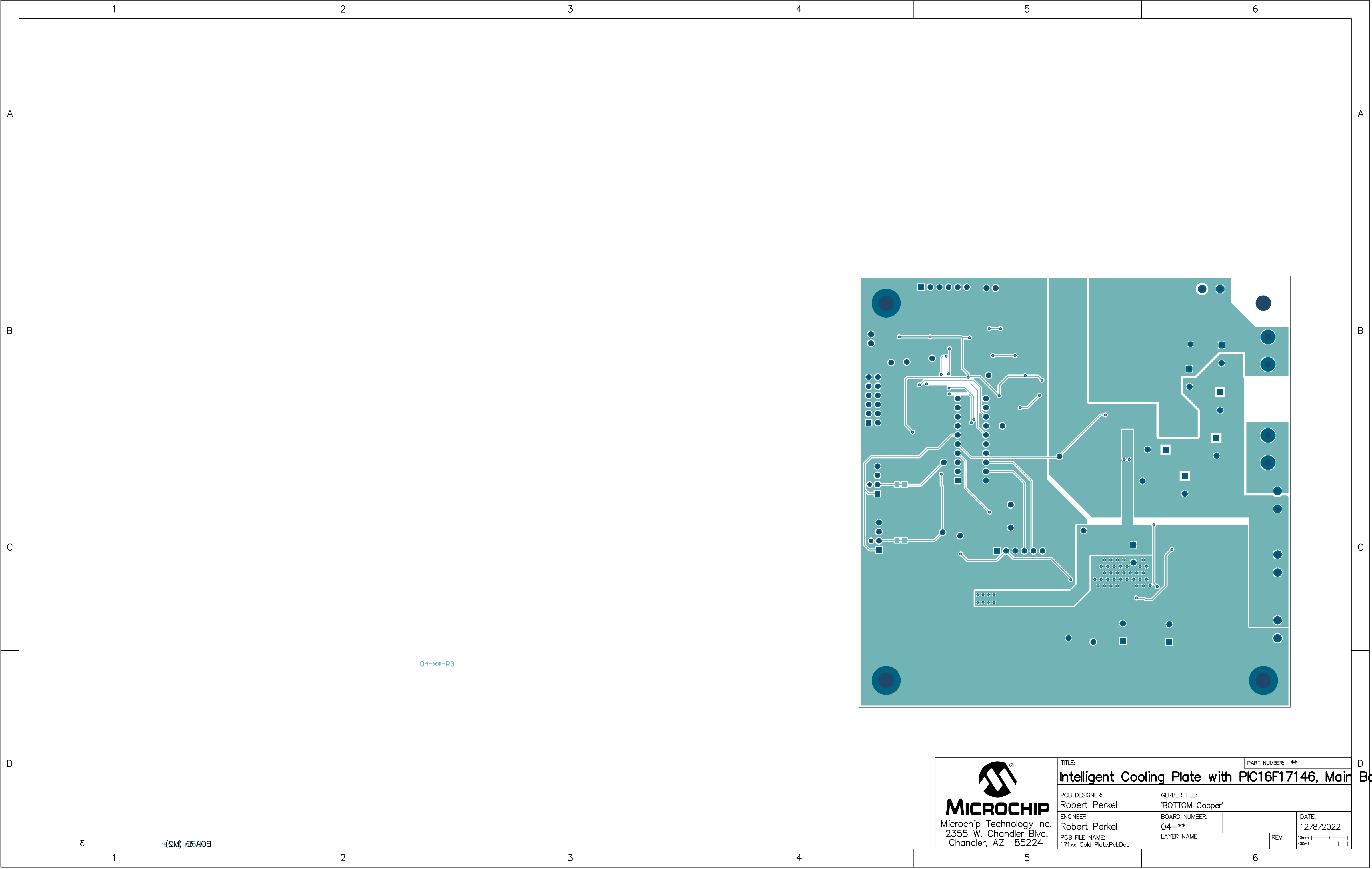
B

C

D

Board





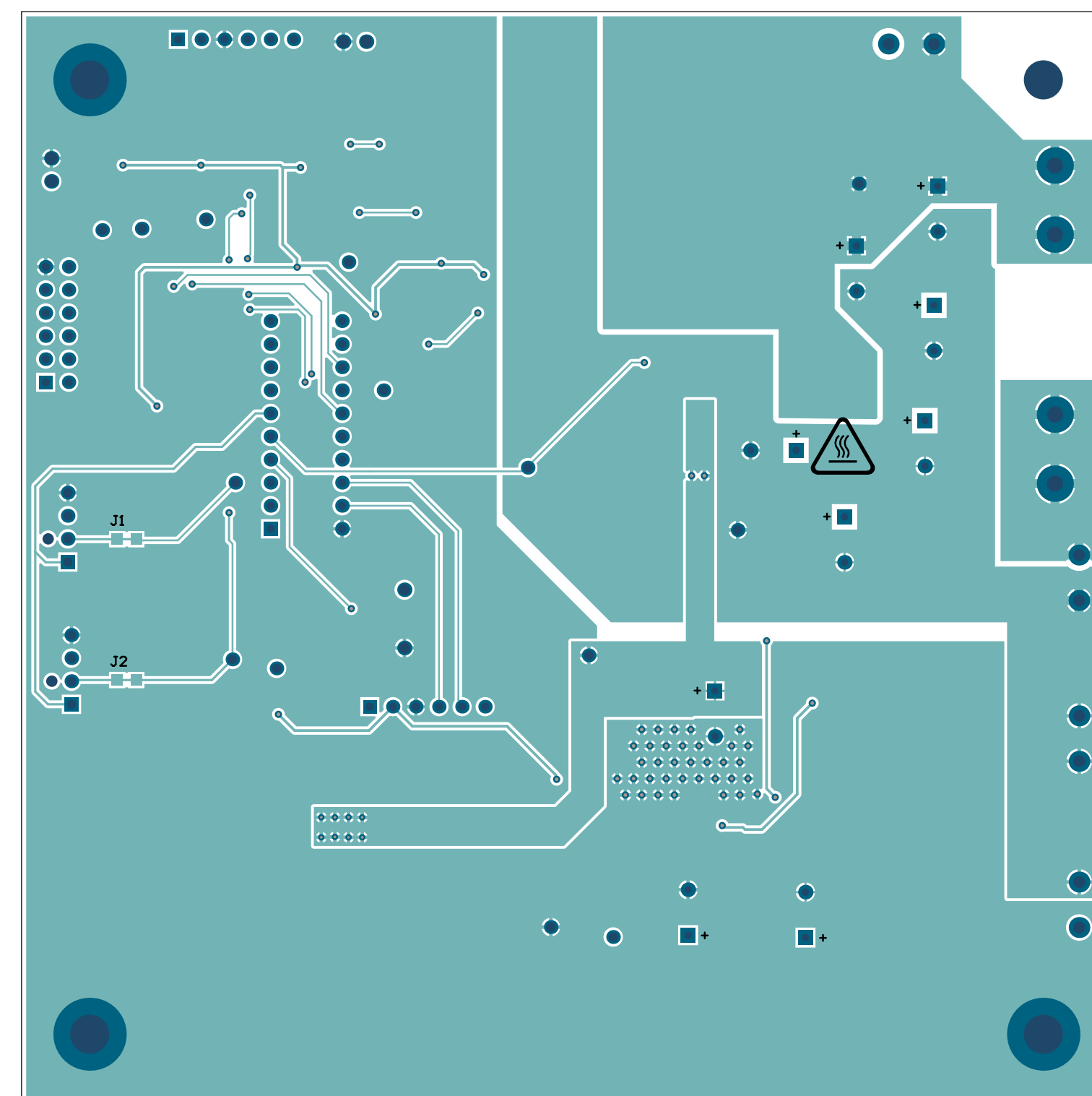
04-**-R3

BOARD (MS) 171



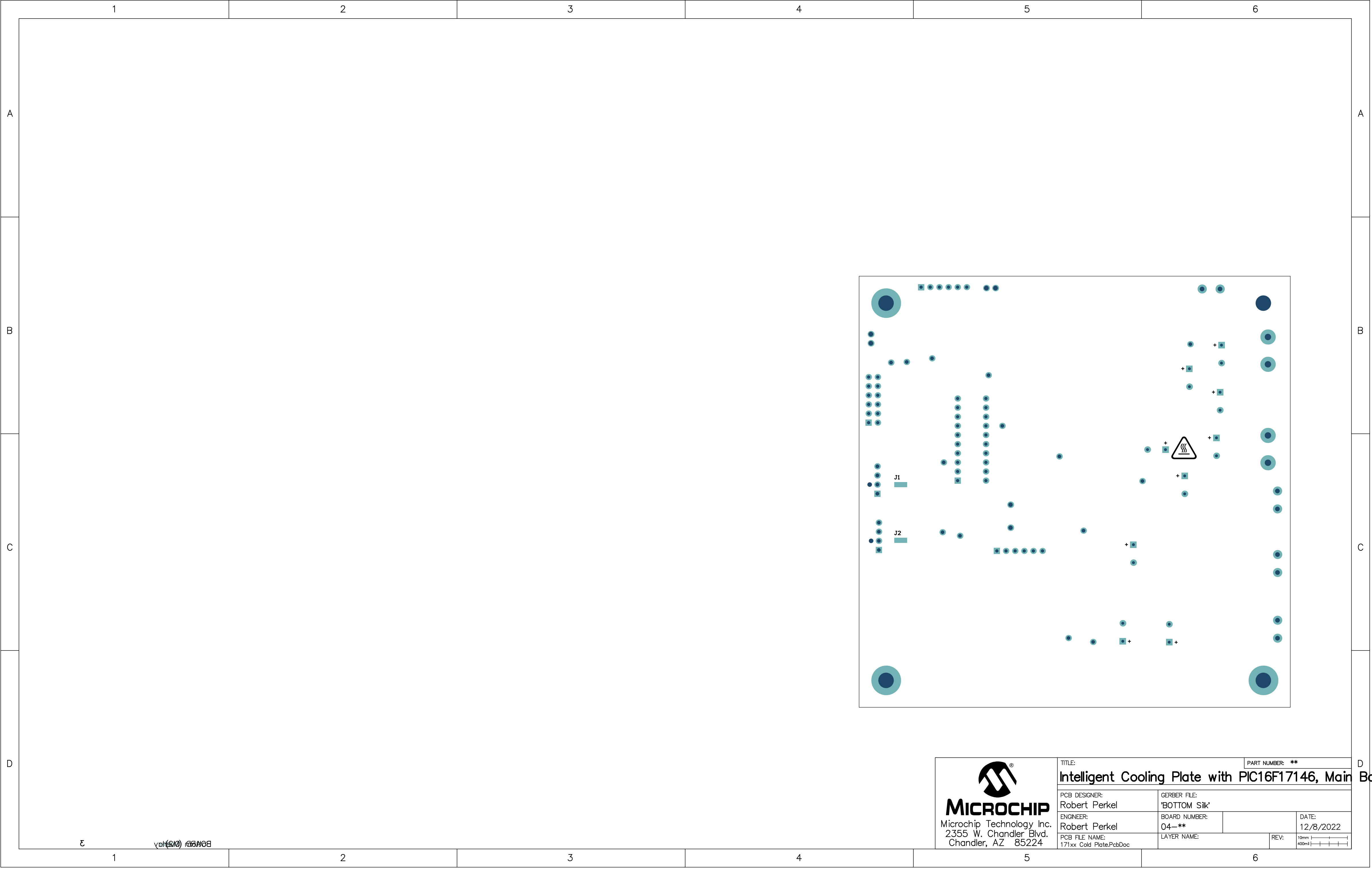
MICROCHIP
Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE:		PART NUMBER: **	
Intelligent Cooling Plate with PIC16F17146, Main Board			
PCB DESIGNER: Robert Perkel		GERBER FILE: 'BOTTOM Copper'	
ENGINEER: Robert Perkel		BOARD NUMBER: 04--**	DATE: 12/8/2022
PCB FILE NAME: 171xx Cold Plate.PcbDoc		LAYER NAME:	REV: <div><div>10mm</div><div>400mil</div><div><div></div><div></div><div></div><div></div><div></div></div></div>



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Chandler, AZ 85224

TITLE:		PART NUMBER: **	
<h1>Intelligent Cooling Plate with PIC16F17146, Main</h1>			
PCB DESIGNER: Robert Perkel		GERBER FILE: 'Bottom Copper & Silk'	
ENGINEER: Robert Perkel		BOARD NUMBER: 04--**	DATE: 12/8/2022
PCB FILE NAME: 171xx_Cold_Plate.PcbDoc	LAYER NAME:	REV:	<div> <div>10mm</div> <div>400m1</div> <div> <div></div> <div></div> <div></div> <div></div> <div></div> </div> </div>





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2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE:		PART NUMBER: **	
Intelligent Cooling Plate with PIC16F17146, Main Board			
PCB DESIGNER: Robert Perkel		GERBER FILE: 'BOTTOM Silk'	
ENGINEER: Robert Perkel		BOARD NUMBER: 04-**	DATE: 12/8/2022
PCB FILE NAME: 171xx_Cold_Plate.PcbDoc		LAYER NAME:	REV: <div><div>10mm</div><div>400mil</div><div><div></div><div></div><div></div><div></div><div></div></div></div>